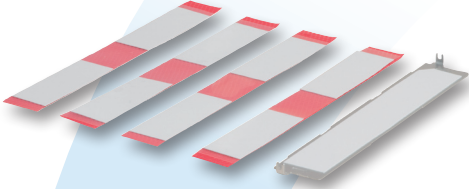


阅读申明

- 1.本站收集的数据手册和产品资料都来自互联网，版权归原作者所有。如读者和版权方有任何异议请及时告之，我们将妥善解决。
- 2.本站提供的中文数据手册是英文数据手册的中文翻译，其目的是协助用户阅读，该译文无法自动跟随原稿更新，同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。
- 3.本站提供的产品资料，来自厂商的技术支持或者使用者的心得体会等，其内容可能存在描述上的差异，建议读者做出适当判断。
- 4.如需与我们联系，请发邮件到marketing@iczoom.com，主题请标有“数据手册”字样。

Read Statement

1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.
2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.
3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.
4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets" .



THIN THERMALLY CONDUCTIVITY ELASTOMERIC INTERFACE MATERIAL

Tflex™ 200T V0 is a specially formulated thin gap filler thermal interface material designed for thin interfaces that require a combination good thermal performance with great reliability. The elastomeric property of Tflex™ 200T V0 provides good thermal performance in a thin interface where reliability, shock and vibration considerations, are critical performance considerations in addition to low thermal resistance.

Tflex™ 200T V0's unique silicone and ceramic filler technology allows a combination of great reliability, good thermal performance, and easy handling.

Tflex™ 200T V0 is slightly tacky, and requires no additional adhesive coating that inhibits thermal performance. Tflex™ 200T V0 is electrically insulating, stable from -40°C thru 200°C and meets UL 94V0 flame rating.

FEATURES AND BENEFITS

- Thermal Conductivity 1.5 W/mK
- Compliant Elastomeric based thin interface material
- Available in 0.008-inch (0.2mm), 0.010-inch (0.25mm), 0.012-inch (0.30mm), 0.015-inch (0.38mm) , and 0.020-inch (0.51mm) thicknesses
- Slightly tacky for adhesion during assembly and transport
- Competitive price for high volume applications
- Available as individual custom parts, sheets, or custom parts converted on a roll

APPLICATIONS

- Memory Modules:
DDR2, DDR3, SDRAM, SRAM, RAM, NVRAM
- LED solid state lighting
- Power electronics

global solutions: local support.™

Americas: +1.800.843.4556

Europe: +49.8031.2460.0

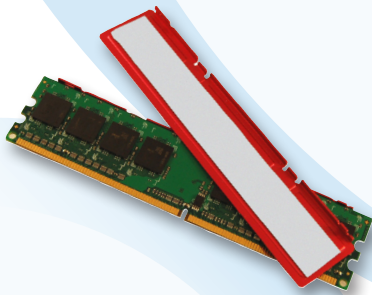
Asia: +86.755.2714.1166

CLV-customerservice@lairdtech.com

www.lairdtech.com/thermal

	8 MIL	10 MIL	15 MIL	TEST METHOD
Construction & Composition	Ceramic filled silicone elastomer	Ceramic filled silicone elastomer	Ceramic filled silicone elastomer, reinforced	
Color	Light Grey	Light Grey	Light Grey	Visual
Thickness	0.008" (0.203mm)	0.010" (0.254mm)	0.015" (0.381mm)	
Thickness tolerance	±0.0015" (±0.038mm)	±0.0015" (±0.038mm)	±0.00225" (±0.057mm)	
Specific Gravity (Density)	2.32 g/cc	2.32 g/cc	2.32 g/cc	Helium Pycnometer
Hardness (Shore 00)	55	55	55	ASTM D2240
Outgassing TML (Post Cured)	0.38%	0.38%	0.38%	ASTM E595
Outgassing CVC (Post Cured)	0.11%	0.11%	0.11%	ASTM E595
UL Flammability Rating	94 V0	94 V0	94 V0	E180840
Temperature Range	-45°C to 200°C	-45°C to 200°C	-45°C to 200°C	
Thermal Conductivity	1.5 W/mK	1.5 W/mK	1.5 W/mK	Hot Disk
Thermal Impedance @ 10 psi @ 69 KPa	0.384°C-in ² /W 2.48°C-cm ² /W	0.488°C-in ² /W 3.14°C-cm ² /W	0.714°C-in ² /W 4.60°C-cm ² /W	ASTM D5470 (modified)
Thermal Expansion (30-150°C)	231.19ppm/°C	231.19ppm/°C	231.19ppm/°C	IPC-TM-650 2.4.2.4
Volume Resistivity	3.5x10 ¹⁰ ohm-cm	3.5x10 ¹⁰ ohm-cm	3.5x10 ¹⁰ ohm-cm	ASTM D257
Dielectric Constant @ 1 MHz	5.0	5.1	5.1	ASTM D150

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.



THR-DS-Tflex-200T-V0 1209

Any information furnished by Laird Technologies and its agents is believed to be accurate and reliable. Responsibility for the use and application of Laird Technologies materials rests with the end user since Laird Technologies and its agents cannot be aware of all potential uses. Laird Technologies makes no warranties as to the fitness, merchantability, or suitability of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies terms and conditions of sale in effect from time to time, a copy of which will be furnished upon request. Laird Technologies' products are sold pursuant to the Laird Technologies' terms and conditions of sale in effect from time to time, a copy of which will be furnished upon request. A1592Z-00 Rev C., 12/2009.